

Flip Chip Technologies Market (By Bumping Technology: Copper Pillar, Solder Bumping, Gold Bumping; By Packaging Technology: 3D IC, 2.5D IC and 2D IC; By Packaging Type: Flip Chip SiP Package, Flip Chip PGA Package, Flip Chip BGA Package, Flip Chip LGA Package, and Wafer Level Packaging–CSPnl; By industry: Electronics, Industrial, Automotive & Transport, Healthcare, IT & Telecommunication, Aerospace and Defense; By Geography: North America, Europe, Asia-Pacific and RoW) Global Scenario, Market Size, Outlook, Trend and Forecast, 2015 – 2024

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Abstracts

As per the latest report published by Variant Market Research, Global flip chip technologies market is estimated to reach \$54 billion by 2024; growing at a CAGR of 9.3% from 2016 to 2024. Flip chip, a semiconductor interconnecting device is commonly used in many electronic products like PCs, smartphones, and medical devices, among others. Flip chip technology offers various benefits such as total package size reduction, reduction in the silicon cost, decrease in signal inductance, and high signal density. Flip chip technology is widely used in various industry verticals such as IT & telecommunication, automotive & transport, electronics, industrial, healthcare, and aerospace and defence, among others.

Major factors driving the global flip chip technologies market are advantages of flip chip

technology than the traditional wire bond electrical connection, evolving internet of things, and rising demand for miniaturization & high-performing electronic devices. However, huge initial investment essential to set up new manufacturing plant may hamper the market growth. Furthermore, high acceptance of sensors in electronic devices would unfold with numerous growth opportunities in the forecasted year.

Major segments of the global flip chip technologies market are bumping technology, packaging type, packaging technology, industry vertical, and geography. Bumping technology comprises copper pillar, gold bumping, solder bumping (tin-lead eutectic solder, and lead-free solder), and other bumping technologies (aluminium & conductive polymer). By, packaging type, the market is categorized as flip chip PGA package, flip chip SiP package, flip chip BGA package, flip chip LGA package, and wafer level packaging–CSPnl. Furthermore, the market is sub segmented by packaging technology as 3D IC, 2.5D IC and 2D IC. Industry vertical is further divided into automotive & transport, electronics, industrial, healthcare, IT & telecommunication, aerospace and defence, and other industry verticals (renewable energy and media & entertainment).

Geographically, the global flip chip technologies market is categorized into North America, Europe, Asia-Pacific and RoW. The U.S., Mexico and Canada are covered under North America wherein Europe covers Germany, France, Italy, and Rest of Europe. Asia-Pacific covers China, Japan, South Korea, Taiwan, India, and Rest of Asia Pacific. Rest of the World (RoW) covers South America, Middle East and Africa.

The major players competing in the market are ASE group, Powertech Technology Inc., United Microelectronics Corporation, Intel Corporation, Siliconware Precision Industries Co., Ltd., Amkor Technology, Inc., TSMC, Jiangsu Changjiang Electronics Technology Co., Ltd., Samsung Electronics Co., and Texas Instruments, Inc., among others.

The key takeaways from the report

The report will provide detailed analysis of Flip Chip Technologies Market with respect to major segments such as bumping technology, packaging type, packaging technology, and industry vertical

The report will include the qualitative and quantitative analysis with market estimation over 2015-2022 and compound annual growth rate (CAGR) between 2016 and 2022.

Comprehensive analysis of market dynamics including factors and opportunities.

An exhaustive regional analysis of Flip Chip Technologies Market.

Profile of key players of the Flip Chip Technologies Market, which include key financials, product & services and new developments.

Scope of Flip Chip Technologies Market

Bumping Technology Segments

Copper Pillar

Gold Bumping

Solder Bumping

Tin-lead eutectic solder

Lead-free solder

Other Bumping Technologies (Aluminium & Conductive polymer)

Packaging Type Segments

Flip Chip PGA Package

Flip Chip SiP Package

Flip Chip BGA Package

Flip Chip LGA Package

Wafer Level Packaging–CSPnl

Packaging Technology Segments

3D IC

2.5D IC

2D IC

Industry Vertical Segments

Automotive & Transport

Electronics

Industrial

Healthcare

IT & telecommunication

Aerospace and Defence

Other Industry Verticals (Renewable Energy and Media & Entertainment)

Geographical Segments

North America

US

Canada

Mexico

Europe

Germany

France

Italy

Rest of Europe

Asia-Pacific

China

Japan

South Korea

Taiwan

India

Rest of Asia-Pacific

RoW

South America

Middle East

Africa

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